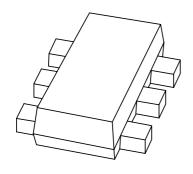
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **PMEG2010EV**Low V<sub>F</sub> MEGA Schottky barrier diode

Product data sheet Supersedes data of 2002 Jun 24 2003 Aug 20



# Low V<sub>F</sub> MEGA Schottky barrier diode

#### PMEG2010EV

#### **FEATURES**

Forward current: 1 AReverse voltage: 20 V

Very low forward voltage

• Ultra small SMD package

• Flat leads: excellent coplanarity and improved thermal behaviour.

#### **APPLICATIONS**

• Low voltage rectification

• High efficiency DC/DC conversion

• Switch mode power supply

• Inverse polarity protection

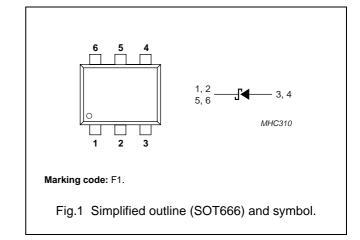
· Low power consumption applications.

#### **DESCRIPTION**

Planar Maximum Efficiency General Application (MEGA) Schottky barrier diode with an integrated guard ring for stress protection in a SOT666 ultra small SMD plastic package.

#### **PINNING**

PIN	DESCRIPTION	
1	cathode	
2	cathode	
3	anode	
4	anode	
5	cathode	
6	cathode	



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		_	20	V
I <sub>F</sub>	continuous forward current		_	1	Α
I <sub>FSM</sub>	non-repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method; note 1	-	8	А
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	125	°C
T <sub>amb</sub>	operating ambient temperature		-65	+125	°C

#### Note

1. Only valid if pins 3 and 4 are connected in parallel.

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# Low V<sub>F</sub> MEGA Schottky barrier diode

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#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	405	K/W
		note 2	215	K/W

#### **Notes**

- 1. Refer to SOT666 standard mounting conditions.
- 2. Mounted on printed circuit-board, 1 cm<sup>2</sup> copper area.

#### Soldering

The only recommended soldering method is reflow soldering.

#### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>F</sub>	continuous forward voltage	I <sub>F</sub> = 10 mA	240	270	mV
		I <sub>F</sub> = 100 mA	300	350	mV
		I <sub>F</sub> = 1000 mA; note 1; see Fig.2	480	550	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 5 V; note 2	5	10	μΑ
		V <sub>R</sub> = 8 V; note 2	7	20	μΑ
		V <sub>R</sub> = 15 V; note 2; see Fig.3	10	50	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 5 V; f = 1 MHz; see Fig.4	19	25	pF

#### **Notes**

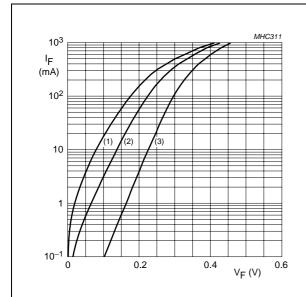
- 1. Only valid if pins 1, 2, 5 and 6 are soldered on a 1 cm<sup>2</sup> copper solder land.
- 2. Pulse test:  $t_p$  = 300  $\mu$ s;  $\delta$  = 0.02.

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# Low V<sub>F</sub> MEGA Schottky barrier diode

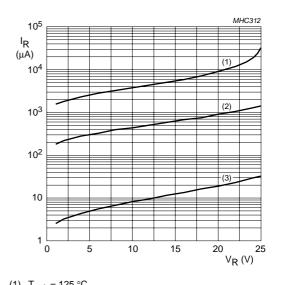
## PMEG2010EV

#### **GRAPHICAL DATA**



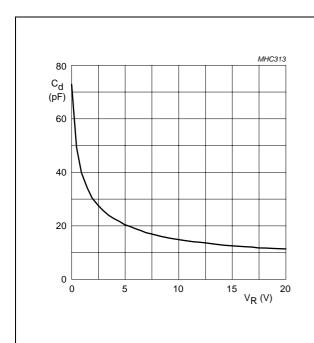
- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.2 Forward current as a function of forward voltage; typical values.



- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2) T<sub>amb</sub> = 85 °C.
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.3 Reverse current as a function of reverse voltage; typical values.



 $f = 1 \text{ MHz}; T_{amb} = 25 \,^{\circ}\text{C}.$ 

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

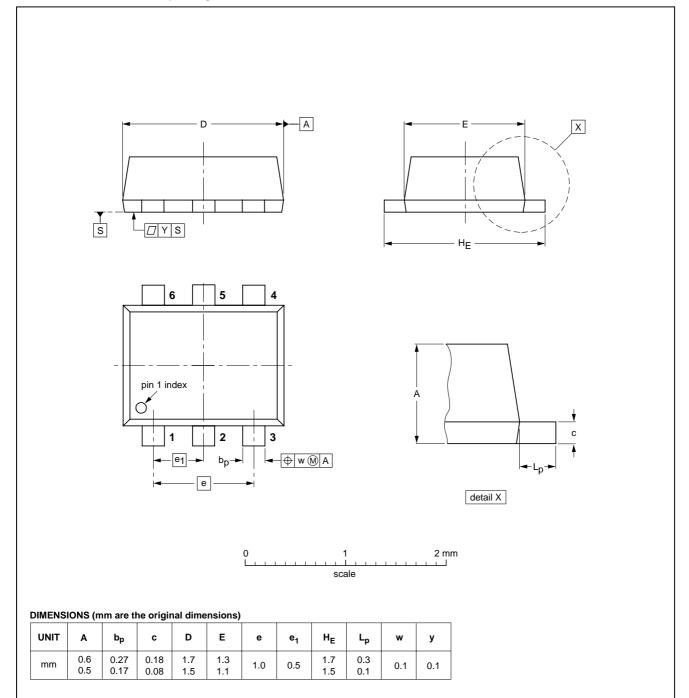
# Low V<sub>F</sub> MEGA Schottky barrier diode

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#### **PACKAGE OUTLINE**

Plastic surface mounted package; 6 leads

SOT666



**REFERENCES** 

EIAJ

**JEDEC** 

**EUROPEAN** 

**PROJECTION** 

**ISSUE DATE** 

<del>-01-01-04</del> 01-08-27

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IEC

OUTLINE VERSION

SOT666

### Low V<sub>F</sub> MEGA Schottky barrier diode

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#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Customer notification**

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#### **Contact information**

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